



DIM1000XSM33-TS001

Single Switch IGBT Module

DS6126-1 October 2013 (LN31016)

FEATURES

- 10.2kV Isolation
- 10µs Short Circuit Withstand
- High Thermal Cycling Capability
- High Current Density Enhanced DMOS SPT
- Isolated AISiC Base With AIN Substrates

APPLICATIONS

- High Reliability Inverters
- Motor Controllers
- Traction Drives
- Choppers

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 1200V to 6500V and currents up to 2400A.

The DIM1000XSM33-TS001 is a single switch 3300V, soft punch through n-channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) plus 10µs short circuit withstand. This device is optimised for traction drives and other applications requiring high thermal cycling capability.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

ORDERING INFORMATION

Order As:

DIM1000XSM33-TS001

Note: When ordering, please use the complete part number

KEY PARAMETERS

V_{CES}		3300V
V _{CE(sat)}	* (typ)	2.2V
l _c ` ´	(max)	1000A
I _{C(PK)}	(max)	2000A

^{*} Measured at the auxiliary terminals

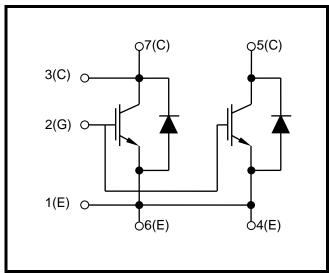


Fig. 1 Circuit configuration

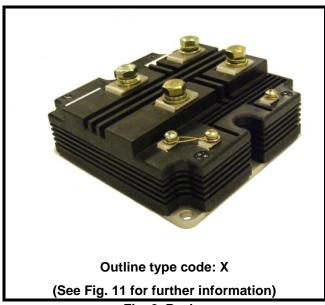


Fig. 2 Package



ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

T_{case} = 25°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
V _{CES}	Collector-emitter voltage	V _{GE} = 0V	3300	V
V _{GES}	Gate-emitter voltage		±20	V
Ic	Continuous collector current	T _{case} = 110°C	1000	Α
I _{C(PK)}	Peak collector current	1ms, T _{case} = 140°C	2000	Α
P _{max}	Max. transistor power dissipation	$T_{case} = 25^{\circ}C, T_{j} = 150^{\circ}C$	10.4	kW
l ² t	Diode l ² t value	$V_R = 0$, $t_p = 10$ ms, $T_j = 125$ °C	320	kA ² s
V _{isol}	Isolation voltage – per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	10.2	kV
Q_{PD}	Partial discharge – per module	IEC1287, V ₁ = 6900V, V ₂ = 5100V, 50Hz RMS	10	рC

THERMAL AND MECHANICAL RATINGS

Internal insulation material:

Baseplate material:

Creepage distance:

Clearance:

CTI (Comparative Tracking Index):

AIN

AISiC

56mm

26mm

>600

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
R _{th(j-c)}	Thermal resistance – transistor	Continuous dissipation – junction to case	-	-	12	°C/kW
R _{th(j-c)}	Thermal resistance – diode	Continuous dissipation – junction to case	-	-	24	°C/kW
R _{th(c-h)}	Thermal resistance – case to heatsink	Mounting torque 5Nm (with mounting grease)	-	-	8	°C/kW
T _j	Junction temperature	Transistor	-	-	150	°C
		Diode	-	-	150	°C
T _{stg}	Storage temperature range	-	-40	-	125	°C
		Mounting – M6	-	-	5	Nm
	Screw torque	Electrical connections – M4	-	-	2	Nm
		Electrical connections – M8	-	-	10	Nm



ELECTRICAL CHARACTERISTICS

 T_{case} = 25°C unless stated otherwise.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
	Collector cut-off current	$V_{GE} = 0V$, $V_{CE} = V_{CES}$			4	mA
I _{CES}		V _{GE} = 0V, V _{CE} = V _{CES} , T _{case} = 125°C			60	mA
		$V_{GE} = 0V$, $V_{CE} = V_{CES}$, $T_{case} = 150$ °C			100	mA
I _{GES}	Gate leakage current	$V_{GE} = \pm 20V, V_{CE} = 0V$			1	μA
V _{GE(TH)}	Gate threshold voltage	$I_C = 80$ mA, $V_{GE} = V_{CE}$		5.7		V
		V _{GE} = 15V, I _C = 1000A		2.2		V
$V_{CE(sat)}^{\dagger}$	Collector-emitter saturation voltage	V _{GE} = 15V, I _C = 1000A, T _j = 125°C		2.8		V
		V _{GE} = 15V, I _C = 1000A, T _j = 150°C		3.0		V
I _F	Diode forward current	DC		1000		Α
I _{FM}	Diode maximum forward current	$t_p = 1 ms$		2000		Α
	Diode forward voltage (IGBT arm)	I _F = 1000A		2.4		V
V_F^{\dagger}		I _F = 1000A, T _j = 125°C		2.5		V
		I _F = 1000A, T _j = 150°C		2.4		V
C _{ies}	Input capacitance	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$		170		nF
Q_g	Gate charge	±15V Including external C _{ge}		17		μC
C _{res}	Reverse transfer capacitance	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz		4		nF
L _M	Module inductance			15		nΗ
R _{INT}	Internal resistance			135		μΩ
SC _{Data}	Short circuit current, I _{SC}	$T_{j} = 150^{\circ}\text{C}, V_{CC} = 2500\text{V}$ $t_{p} \le 10\mu\text{s}, V_{GE} \le 15\text{V}$ $V_{CE (max)} = V_{CES} - L^{*} x dI/dt$ IEC 60747-9		3700		А

Note:

[†] Measured at the auxiliary terminals

L is the circuit inductance + L_M



ELECTRICAL CHARACTERISTICS

T_{case} = 25°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
t _{d(off)}	Turn-off delay time	I _C = 1000A		1.9		μs
t _f	Fall time	$V_{GE} = \pm 15V$		520		ns
E _{OFF}	Turn-off energy loss	$V_{CE} = 1800V$		1800		mJ
t _{d(on)}	Turn-on delay time	$R_{G(ON)} = 2.2\Omega$ $R_{G(OFF)} = 2.2\Omega$		560		ns
t _r	Rise time	$C_{qe} = 220nF$		360		ns
E _{ON}	Turn-on energy loss	L _s ~ 100nH		1300		mJ
Q_{rr}	Diode reverse recovery charge	I _F = 1000A		600		μC
l _{rr}	Diode reverse recovery current	V _{CE} = 1800V		680		Α
E _{rec}	Diode reverse recovery energy	dI _F /dt = 2700A/μs		750		mJ

T_{case} = 125°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
t _{d(off)}	Turn-off delay time	I _C = 1000A		2.0		μs
t _f	Fall time	$V_{GE} = \pm 15V$		570		ns
E _{OFF}	Turn-off energy loss	$V_{CE} = 1800V$		2000		mJ
t _{d(on)}	Turn-on delay time	$R_{G(ON)} = 2.2\Omega$ $R_{G(OFF)} = 2.2\Omega$		550		ns
t _r	Rise time	$C_{qe} = 220nF$		420		ns
E _{ON}	Turn-on energy loss	L _S ~ 100nH		1600		mJ
Q _{rr}	Diode reverse recovery charge	I _F = 1000A		935		μC
I _{rr}	Diode reverse recovery current	V _{CE} = 1800V		775		Α
E _{rec}	Diode reverse recovery energy	dI _F /dt = 2700A/μs		1200		mJ

T_{case} = 150°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
t _{d(off)}	Turn-off delay time	I _C = 1000A		2.0		μs
t _f	Fall time	$V_{GE} = \pm 15V$		580		ns
E _{OFF}	Turn-off energy loss	$V_{CE} = 1800V$		2100		mJ
t _{d(on)}	Turn-on delay time	$R_{G(ON)} = 2.2\Omega$ $R_{G(OFF)} = 2.2\Omega$		550		ns
t _r	Rise time	$C_{qe} = 220 nF$		430		ns
E _{ON}	Turn-on energy loss	L _S ~ 100nH		1750		mJ
Q _{rr}	Diode reverse recovery charge	I _F = 1000A		1100		μC
I _{rr}	Diode reverse recovery current	V _{CE} = 1800V		825		Α
E _{rec}	Diode reverse recovery energy	dl _F /dt = 2700A/μs		1450		mJ



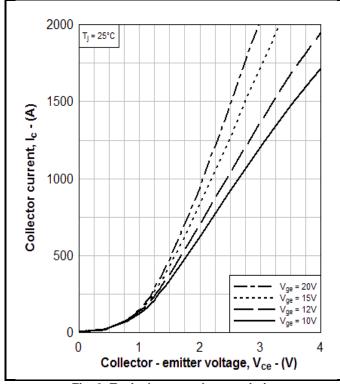


Fig. 3 Typical output characteristics

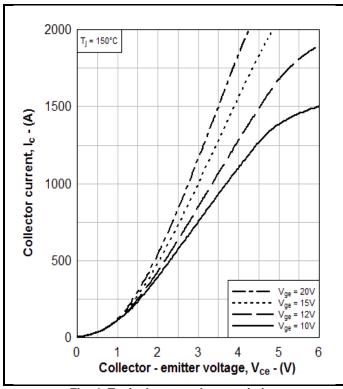


Fig. 4 Typical output characteristics

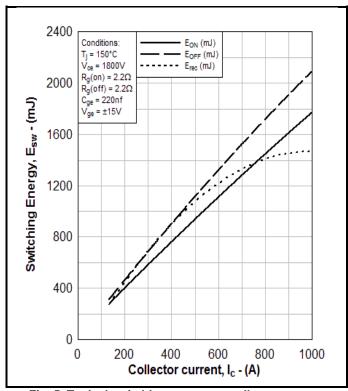


Fig. 5 Typical switching energy vs collector current

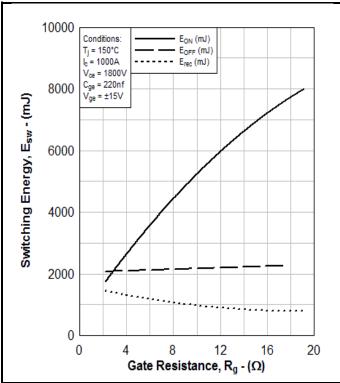


Fig. 6 Typical switching energy vs gate resistance



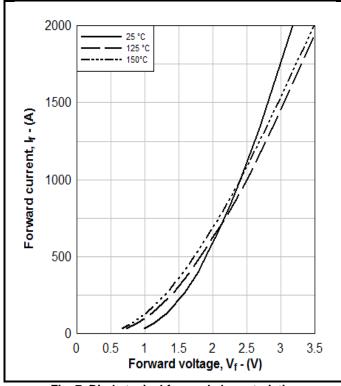


Fig. 7 Diode typical forward characteristics

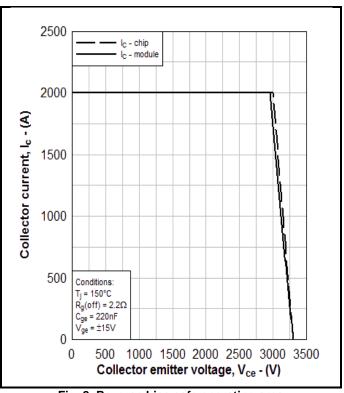


Fig. 8 Reverse bias safe operating area

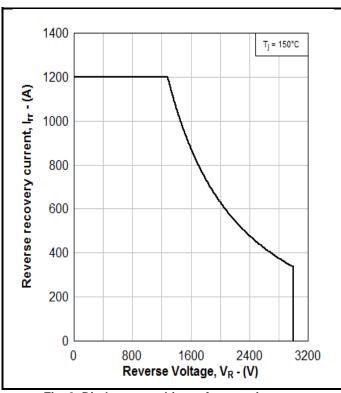


Fig. 9 Diode reverse bias safe operating area

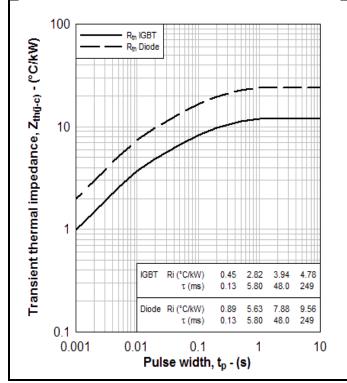


Fig. 10 Transient thermal impedance



PACKAGE DETAILS

For further package information, please visit our website or contact Customer Services. All dimensions in mm, unless stated otherwise.

DO NOT SCALE.

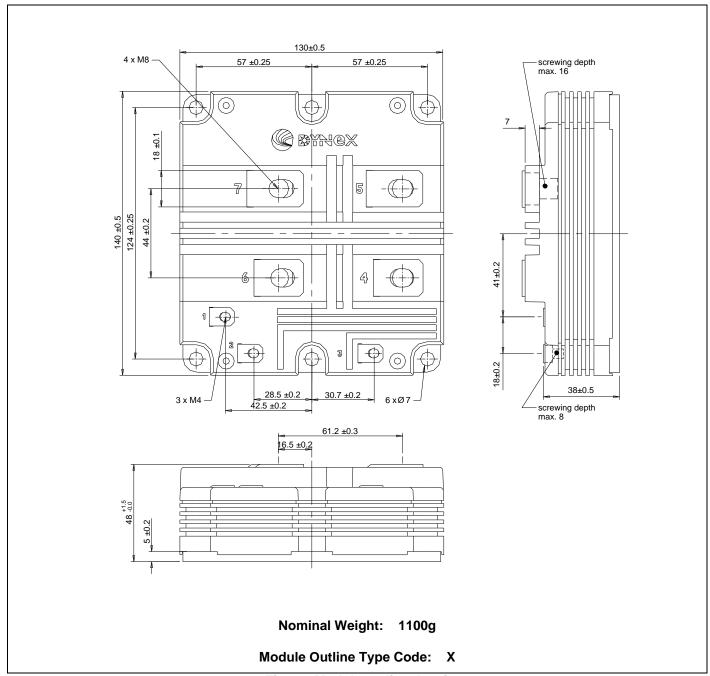


Fig. 11 Module outline drawing



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